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Components, Hybrids, and Manufacturing Technology, IEEE Transactions on [also IEEE Trans. on Components, Packaging, and Manufacturing Technology, A, B, C], Volume: 2, Issue: 2, Jun 1979

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2 Low-resistivity PVD /spl alpha/-tantalum: phase formation and integration in ultra-low k dielectric/copper damascene structures*Donohue, H.; Gris, H.; Yeoh, J.C.; Buchanan, K.;*

Interconnect Technology Conference, 2002. Proceedings of the IEEE 2002 International, 3-5 June 2002

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3 A Method of Reducing Cost in the Production of High Stability Thin-film RC Networks*Arcidiacono, F.; Duff, O.; Koerckel, G.;*

Components, Hybrids, and Manufacturing Technology, IEEE Transactions on [also IEEE Trans. on Components, Packaging, and Manufacturing Technology, A, B, C], Volume: 3, Issue: 4, Dec 1980

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